ASSOCIATION ELECTRONICS	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information					
Supplier	Information															
Company name*				ompany unique ID			Unique ID Authority					Response Date*				
onsemi												2025-08-01				
Contact Na	nme	Title - Contact			]	Phone - Contact*				Email - Contact*						
Product-E	nv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Authorized	Representative*	Title - Representative			]	Phone - Representative*				Email - Representative*						
Product-E	nv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Da	ate Version Manufacturing Site		V	Veight*	UON	M	Unit Type		
		NRVTS360ETFSWFT 3A 60V Trench Scho		hottky u8FL w	ettable	2025-08-01	25-08-01			3	2.25	mg		Each		
Manufac	cturing Proccess Informa	ntion														
·F	Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-	-STD-020 MSL	020 MSL Rating Peak Process Body Temperature Max Time at Pe					ne at Peak	Temperati	ıre Nu	umber of Refl	low Cycles	
Matte Tin (Sn) - annealed CU Alloy 1					260		С	30		second	ls 3					
omments																
vel 1 - ma	aximum time at peak temperat	ure during so	ldering is 10-3	0 seconds												
or more i	nformation regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier has not originally be the sole and exclusivesource of the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-6_									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	2.98	mg	Supplier	Zinc (Zn)	7440-66-6		0.0036	mg
			Supplier	Iron (Fe)	7439-89-6		0.07	mg
			Supplier	Copper (Cu)	7440-50-8		2.9055	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0009	mg
Die	0.47	mg	Supplier	Silicon (Si)	7440-21-3		0.47	mg
Die Attach Solder	0.79	mg	Supplier	Silver (Ag)	7440-22-4		0.0198	mg
			A	Lead (Pb)	7439-92-1	7a	0.7308	mg
			Supplier	Tin (Sn)	7440-31-5		0.0395	mg
Lead Frame	12.27	mg	Supplier	Iron (Fe)	7439-89-6		0.0123	mg
			Supplier	Copper (Cu)	7440-50-8		12.254	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0037	mg
Lead Frame plating	0.14	mg	Supplier	Silver (Ag)	7440-22-4		0.14	mg
Mold Compound-Black	15.0	mg		Epoxy resin	proprietary data		1.125	mg
			Supplier	Phenolic Resin	Proprietary Data		0.375	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.125	mg
			Supplier	Carbon Black (C)	1333-86-4		0.075	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		12.3	mg
Plating	0.6	mg	Supplier	Tin (Sn)	7440-31-5		0.6	mg